

FEATURES

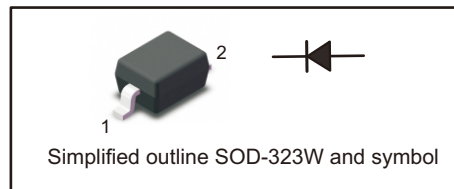
- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SOD-323W
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 5.48mg / 0.00019oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings at 25°C

Parameter	Symbols	1N4148JGB	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Average Rectified Forward Current	$I_{F(AV)}$	150	mA
Non-repetitive Peak Forward Surge Current at 1s at 1ms at 1us	I_{FSM}	0.5 1 4	A
Total Power Dissipation	P_{tot}	400	mW
Typical Thermal Resistance (1)	$R_{\theta JA}$ $R_{\theta JC}$	340 120	°C/W
Operating and Storage Temperature Range	$T_j T_{stg}$	-55 ~ +150	°C

(1) P.C.B. mounted with 5*5mm copper pad areas.

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbols	1N4148JGB	Units
Reverse Breakdown Voltage at $I_R=1\mu\text{A}$	$V_{(BR)R}$	100	V
Maximum Forward Voltage at 1 m A at 10 m A at 50 m A at 150 m A	V_F	0.715 0.855 1.00 1.25	V
Peak Reverse Current at $V_R=20\text{V}$ $T_j=25^\circ\text{C}$ at $V_R=75\text{V}$ $T_j=25^\circ\text{C}$ at $V_R=25\text{V}$ $T_j=150^\circ\text{C}$ at $V_R=75\text{V}$ $T_j=150^\circ\text{C}$	I_R	0.025 1 30 50	μA
Typical Junction Capacitance $f=1\text{MHz}, V_R=0\text{V}$	C_j	5	pF
Typical Reverse Recovery Time (2)	t_{rr}	4	ns

(2) Measured with $I_F=I_R=10\text{mA}$, $I_{rr}=0.1 \times I_R$, $R_L=100\Omega$



Typical Performance Characteristics

Fig.1 Power Derating Curve

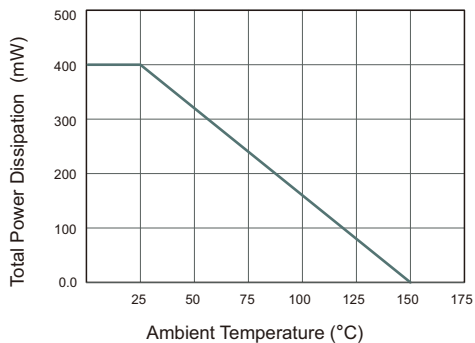


Fig.2 Typical Reverse Characteristics

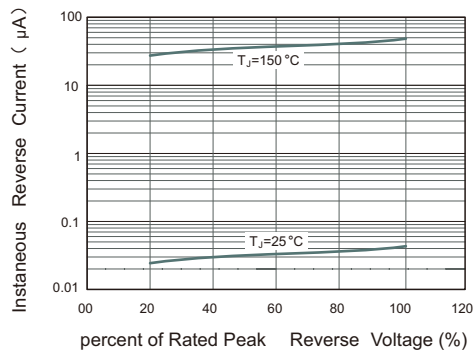


Fig.3 Typical Instantaneous Forward Characteristics

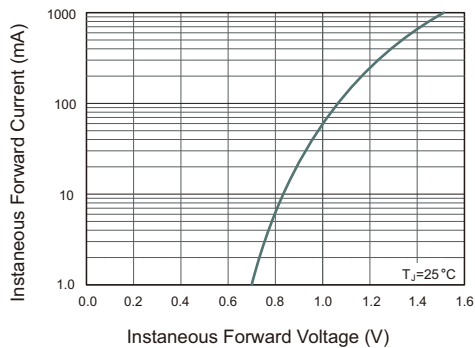
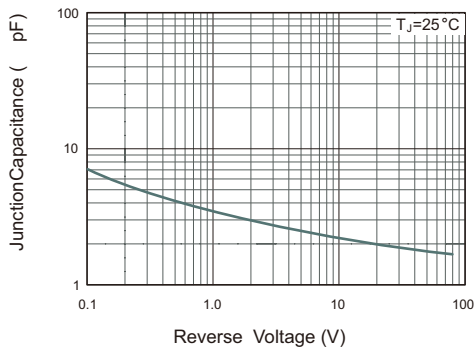


Fig.4 Typical Junction Capacitance

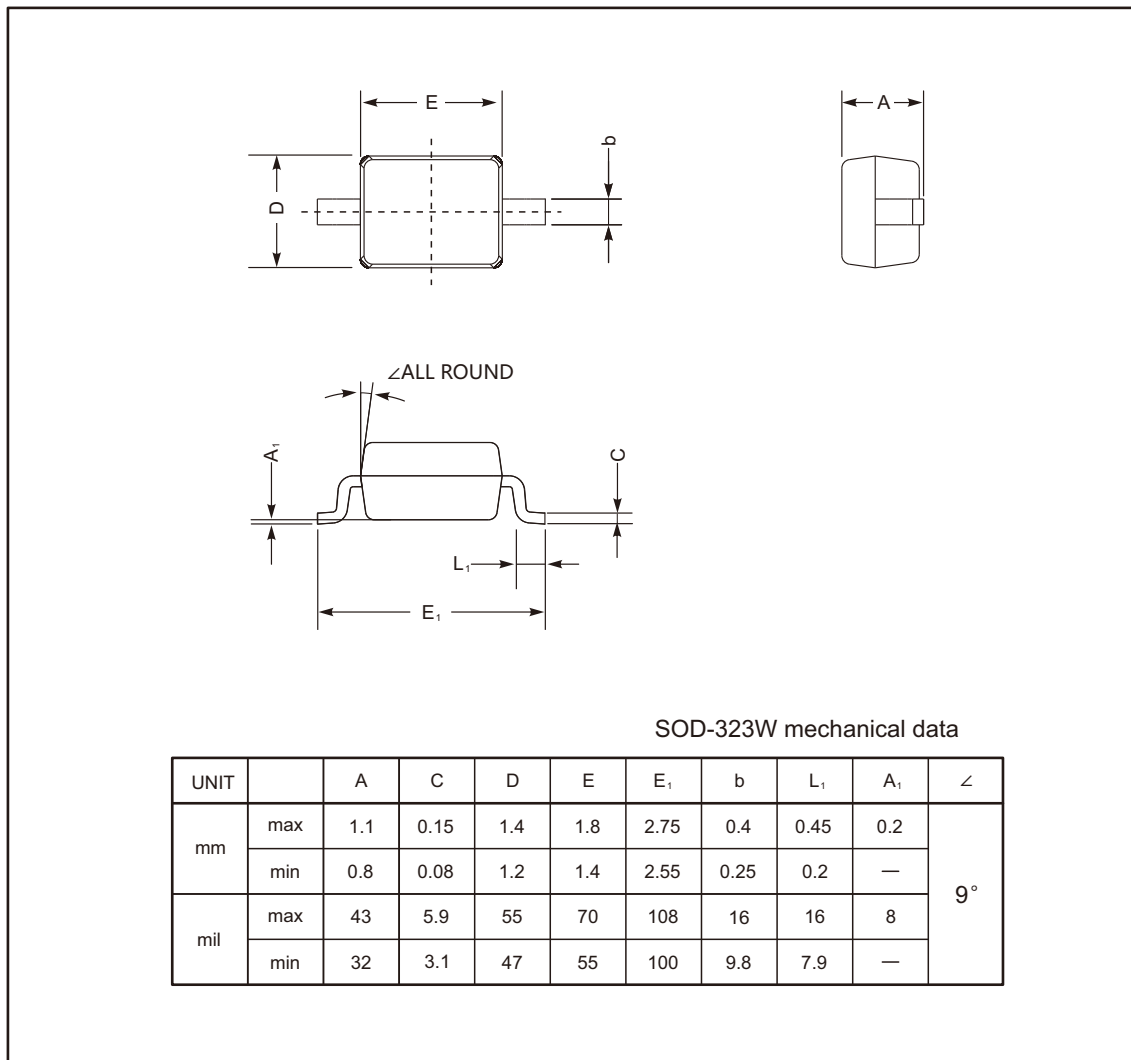




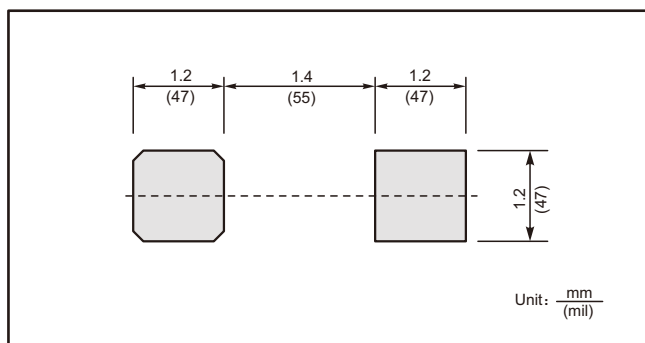
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323W



The recommended mounting pad size



Marking

Type number	Marking code
1N4148JGB	4J



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